

**AMENDMENTS TO THE SPECIFICATION**

Please amend Paragraph [0012] as follows:

**[0012]** Referring now to Figure 1, which is an illustration of an electronics assembly 10 in accordance with the present invention. The electronics assembly 10 includes a heat generating component 12 and a heat sink 14. In one embodiment, the heat generating component 12 is an electronic component that generates heat during operation, although a variety of heat generating components 12 are contemplated. Similarly, a wide variety of heat sinks 14 are known in the prior art and contemplated by the present invention. Heat sinks 14 may take the form of metal cases, heat rail components, brackets, fins, or a variety of other configurations.